



# ISMI 2018 & IEEE SMILE 2018

International Symposium on Semiconductor Manufacturing and  
Intelligence & IEEE International Conference on Smart Manufacturing,  
Industrial & Logistics Engineering



February 7-9, 2018, Hsinchu, Taiwan

- 31 Human-System Cooperative Hybrid Augmented Intelligence Based Dynamic Dispatching  
Framework of Semiconductor Wafer Fabrication Facility  
*Li Li and Cui Meiji*
- 44 The Economic and Sustainable Influence of Package Sizes in a Packaging System  
*Wu-Hsun Chung, Ming-Chuan Chiu and Hsin-Han Lin*
- 55 On Location Strategy Model of Vending Machines: Impact Analysis of Their Relocation for  
Competitive Advantage  
*Tetsuya Sato and Hiroshi Katayama*
- 62 Dynamic Dispatching of Inequivalent Machines with Dispatching-Dependent Deterioration  
*Yi-Chun Yao, Chih-Chuan Chang and Cheng-Hung Wu*



**ISMI**



清華-台積電 卓越製造中心  
NTHU-TSMC Center for Manufacturing Excellence

